



## DESCRIPTION:

The *highly efficient* Model SCS112 is the ideal solution for submicron cleaning of Substrates including mounted Sawed/Scribed Wafers and other. This *very reliable* and *cost effective* system utilizes a *proven* High Pressure De- ionized Water or Atomizing Mist Nozzle. The Rapid and Effective Drying technique uses High Spin Speeds and Nitrogen Assist. The SCS112 is capable of processing the wafer output of up to three saws while cleaning consistent with the most strenuous bonding and packaging requirements.

## FEATURES:

- Up to 8 Inch Wafer Compatibility Including Unmounted Wafers, as well as Tape Ring and Film Frame mounted Wafers.
- Oscillating High Pressure D.I. Water Fan Jet Assembly (Up to 1500 or 2000 PSI depending on configuration) or Atomizing Mist Nozzle, for Effective and Efficient Cleaning.
- Nitrogen Blow-off for Rapid and Effective Drying and Nitrogen Wafer Lift at end of Cycle
- Microprocessor controlled with multiple recipe, retention
- DC Brushless spindle motor with variable speed selection
- D.I. Water Line Purge for a Bacteria Free System
- Built-in Safety Interlocks and Positive Lid Locking During Process Cycle.

## OPTIONS:

- Chucks, for up to Eight (8) Inch Unmounted Wafers, Eight (8) Inch Tape Ring and Film Frame Mounted Wafers. All Chucks have Vacuum Hold-down and Film Frame having Positive Lock
- Infrared Heat Lamp for Complete Drying
- CO<sub>2</sub> Re-ionizer for Elimination of Static Charge
- Built-in Exhaust Blower for Consistent Results
- Venturi Vacuum Generator



## FACILITIES REQUIREMENTS:

Power:	220 VAC, 10 Amps, 50/60 Hz
D.I. Water:	50 – 70 PSI, 0.5 GPM
Nitrogen:	70 PSI & 1CFM Minimum
CDA:	80 PSI (Min/Max) & 7.0 CFM
Vacuum:	21 Inches Mercury Minimum
Exhaust:	150CFM Three (3) Inch Port
Drain:	0.5 GPM Intermittent
CO <sub>2</sub> :	50 PSI 0.025 CFM
Dimensions:	26" Wide x 21" Deep x 40" High
Weight:	~200 Pounds